



PMEG6020EP

2 A low VF MEGA Schottky barrier rectifier

28 February 2019

Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 2$ A
- Reverse voltage: $V_R \leq 60$ V
- Low forward voltage
- High power capability due to clip-bond technology
- AEC-Q101 qualified
- Small and flat lead SMD plastic package
- Capable for reflow and wave soldering

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data



Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|-------------|-------------------------|--|-----|-----|-----|-----|---------|
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20$ kHz; $T_{amb} \leq 85$ °C; square wave | [1] | - | - | 2 | A |
| | | $\delta = 0.5$; $f = 20$ kHz; $T_{sp} \leq 140$ °C; square wave | | - | - | 2 | A |
| V_R | reverse voltage | $T_j = 25$ °C | | - | - | 60 | V |
| V_F | forward voltage | $I_F = 2$ A; $T_j = 25$ °C | | - | 460 | 530 | mV |
| I_R | reverse current | $V_R = 60$ V; $T_j = 25$ °C | | - | 60 | 150 | μ A |

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|------------------------|--|---|
| 1 | K | cathode ^[1] |  CFP5 (SOD128) |  sym001 |
| 2 | A | anode | | |

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PMEG6020EP | CFP5 | plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body | SOD128 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMEG6020EP | AA |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|-------------|-------------------------------------|--|-----|-----|------|------|
| V_R | reverse voltage | $T_j = 25\text{ °C}$ | | - | 60 | V |
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20\text{ kHz}$; $T_{amb} \leq 85\text{ °C}$; square wave | [1] | - | 2 | A |
| | | $\delta = 0.5$; $f = 20\text{ kHz}$; $T_{sp} \leq 140\text{ °C}$; square wave | | - | 2 | A |
| I_{FSM} | non-repetitive peak forward current | $t_p = 8\text{ ms}$; square wave; $T_{j(init)} = 25\text{ °C}$ | | - | 50 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [2] | - | 625 | mW |
| | | | [3] | - | 1.05 | W |
| | | | [1] | - | 2.1 | W |
| T_j | junction temperature | | | - | 150 | °C |
| T_{amb} | ambient temperature | | | -55 | 150 | °C |
| T_{stg} | storage temperature | | | -65 | 150 | °C |

[1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------|--|-------------|---------|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] [2] | - | - | 200 | K/W |
| | | | [1] [3] | - | - | 120 | K/W |
| | | | [1] [4] | - | - | 60 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [5] | - | - | 12 | K/W |

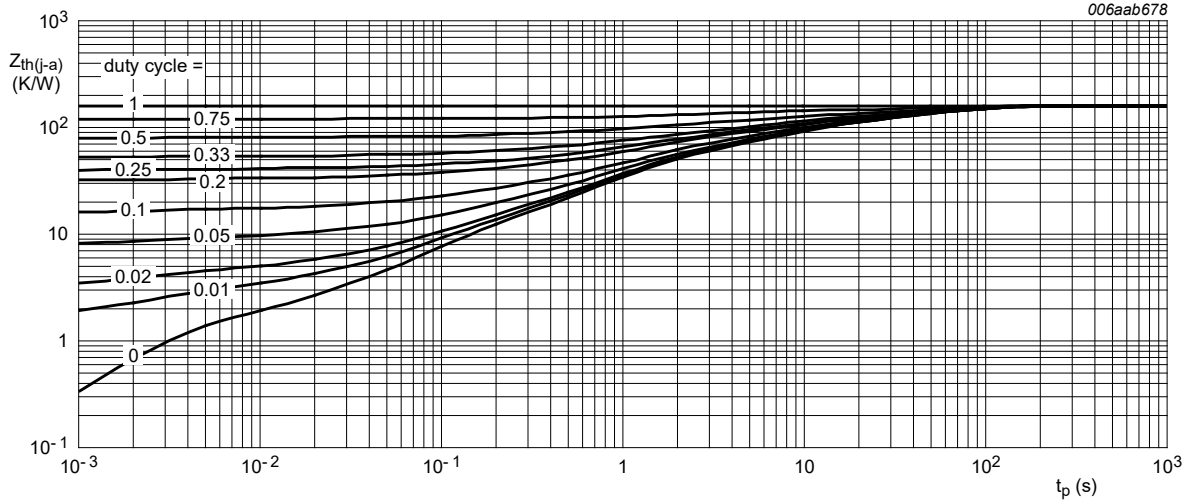
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

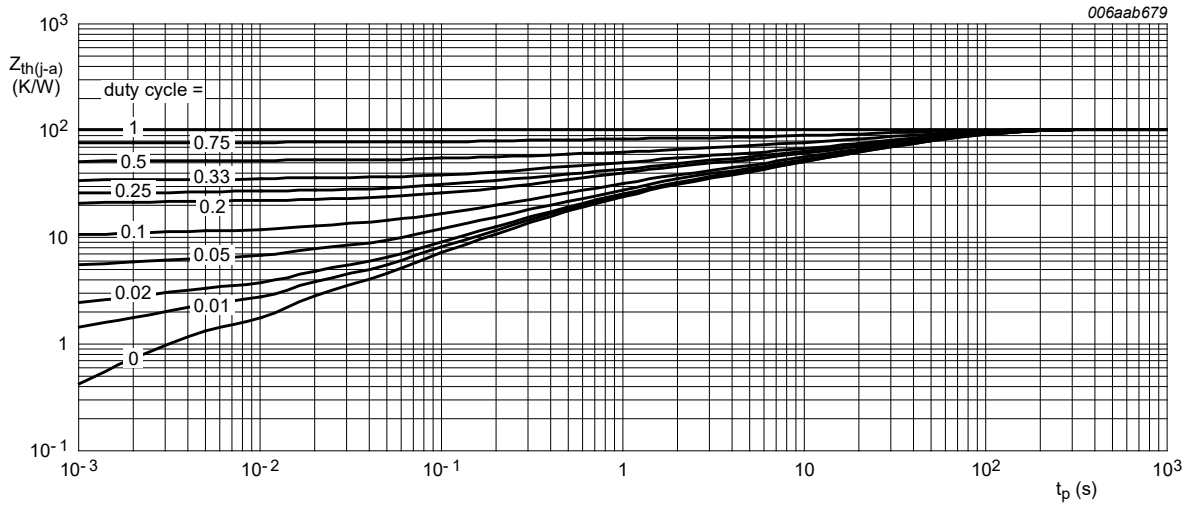
[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

[5] Soldering point of cathode tab.



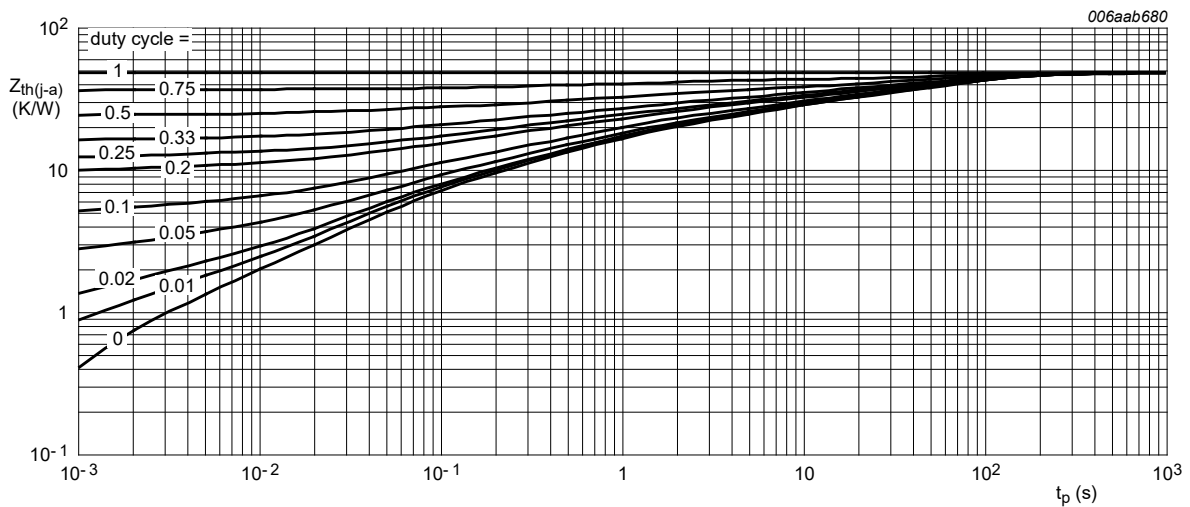
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



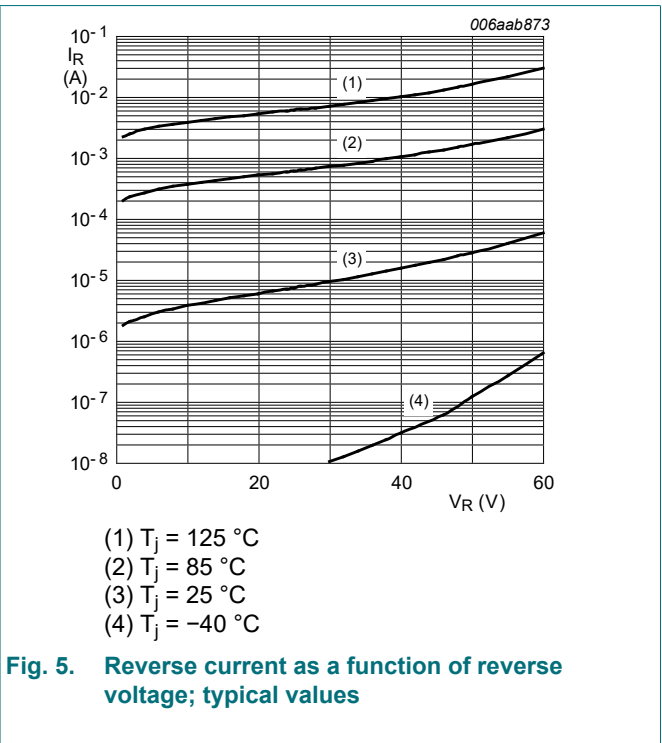
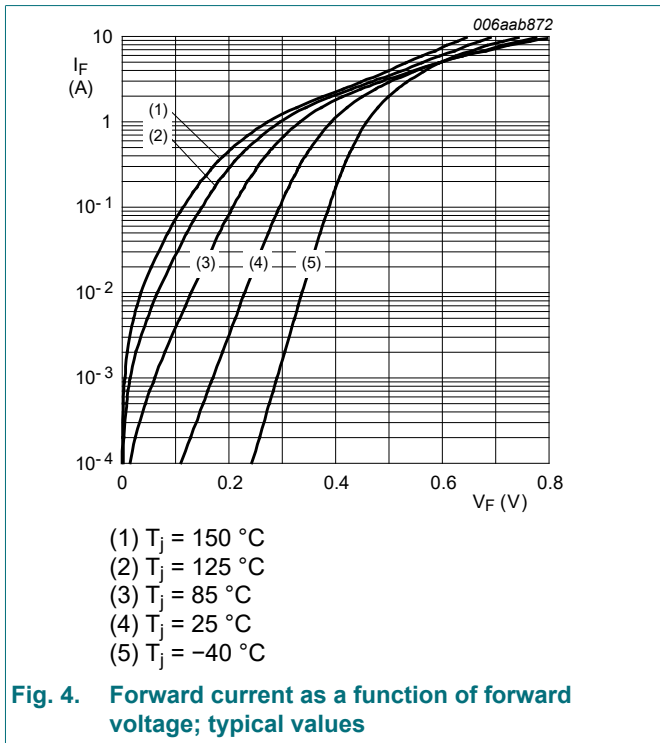
Ceramic PCB, Al₂O₃, standard footprint

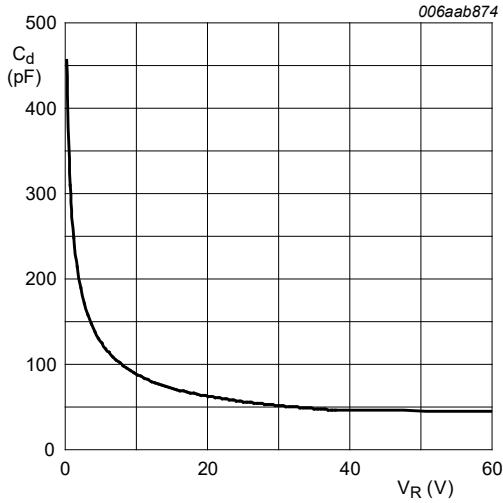
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

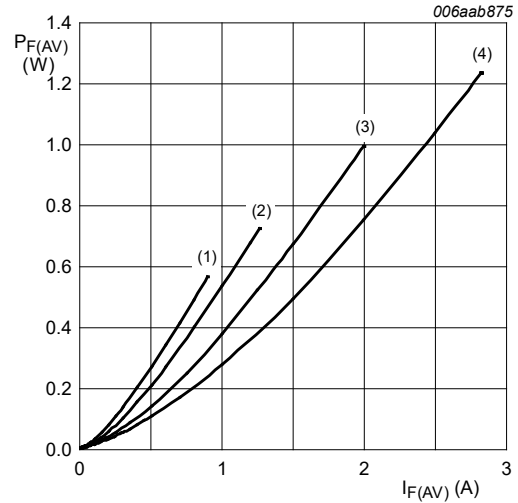
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|-------------------|--|-----|-----|-----|------|
| V _F | forward voltage | I _F = 0.1 A; T _j = 25 °C | - | 300 | 340 | mV |
| | | I _F = 0.5 A; T _j = 25 °C | - | 360 | 420 | mV |
| | | I _F = 1 A; T _j = 25 °C | - | 400 | 460 | mV |
| | | I _F = 1.5 A; T _j = 25 °C | - | 430 | 500 | mV |
| | | I _F = 2 A; T _j = 25 °C | - | 460 | 530 | mV |
| I _R | reverse current | V _R = 5 V; T _j = 25 °C | - | 2.5 | - | μA |
| | | V _R = 10 V; T _j = 25 °C | - | 3.5 | - | μA |
| | | V _R = 60 V; T _j = 25 °C | - | 60 | 150 | μA |
| C _d | diode capacitance | V _R = 1 V; f = 1 MHz; T _j = 25 °C | - | 240 | - | pF |
| | | V _R = 10 V; f = 1 MHz; T _j = 25 °C | - | 80 | - | pF |





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

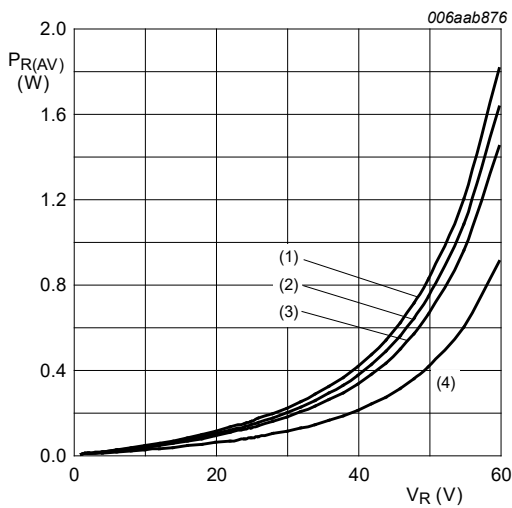
Fig. 6. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

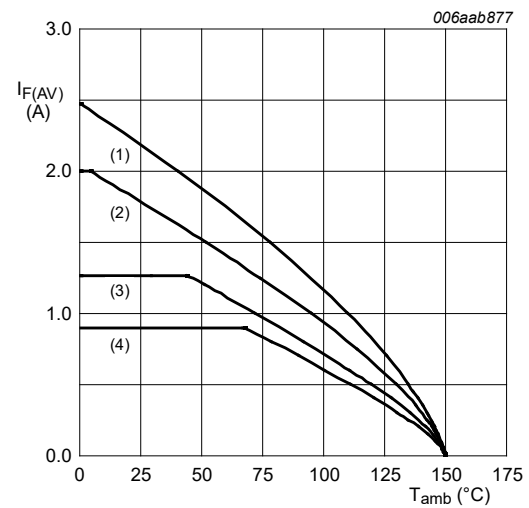
Fig. 7. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

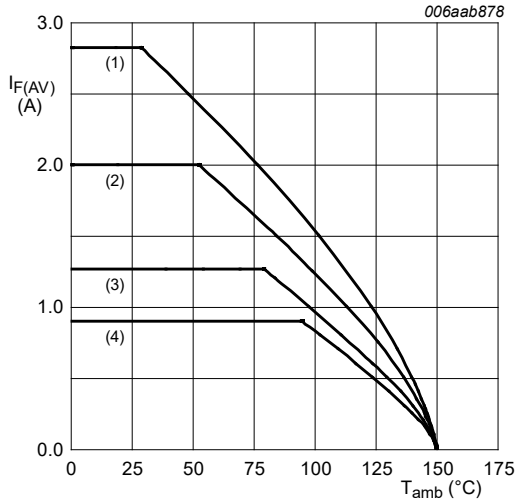


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

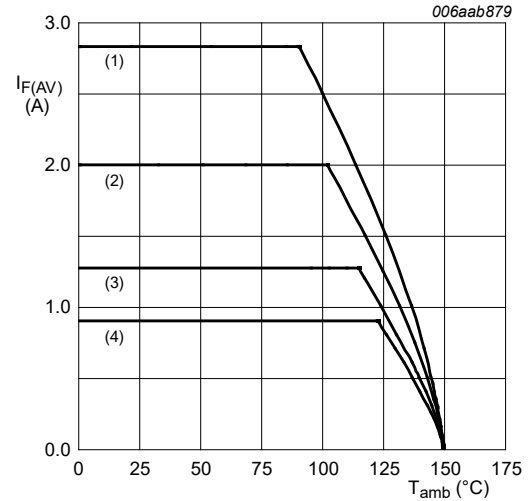
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.5; f = 20 \text{ kHz}$
- (3) $\delta = 0.2; f = 20 \text{ kHz}$
- (4) $\delta = 0.1; f = 20 \text{ kHz}$

Fig. 9. Average forward current as a function of ambient temperature; typical values



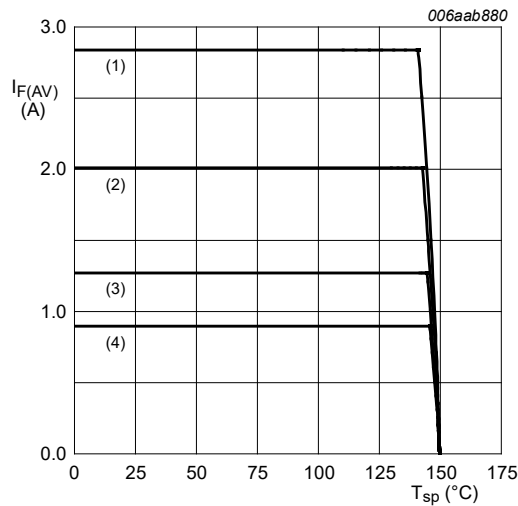
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information

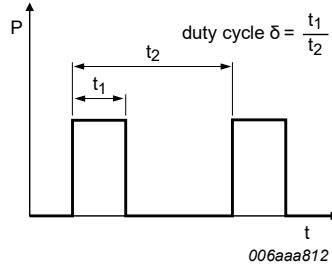


Fig. 13. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

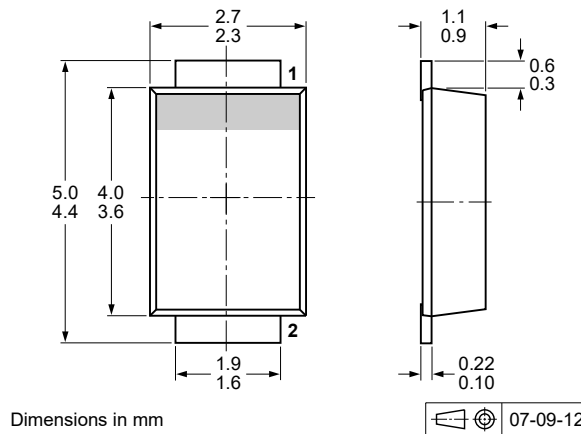


Fig. 14. Package outline CFP5 (SOD128)

13. Soldering

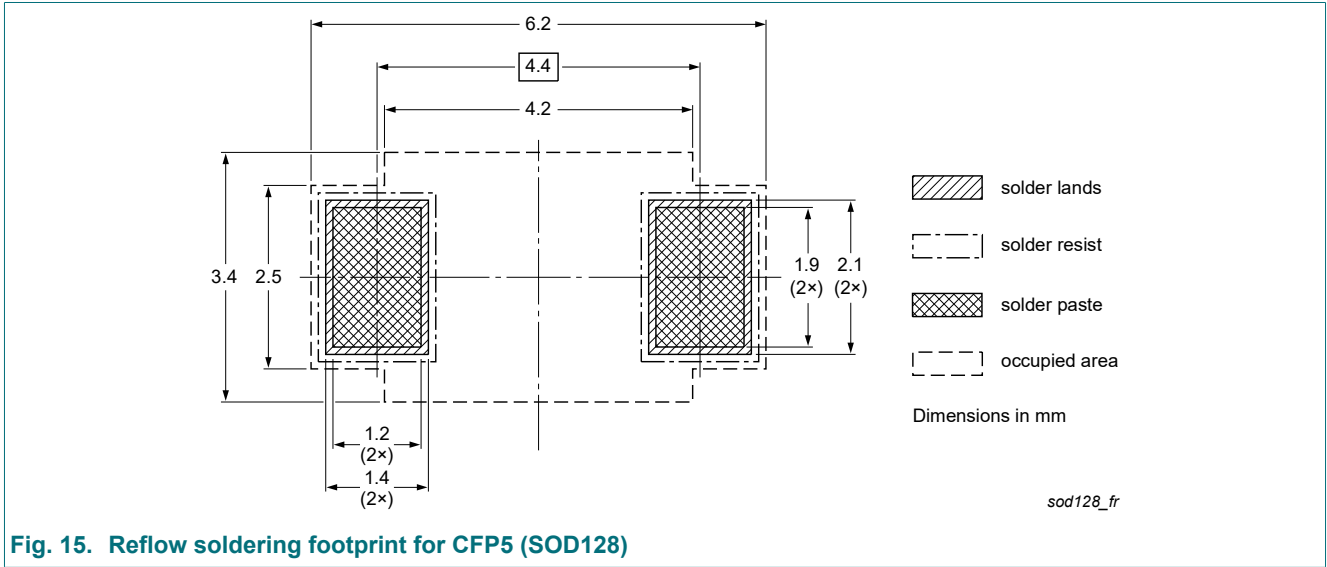


Fig. 15. Reflow soldering footprint for CFP5 (SOD128)

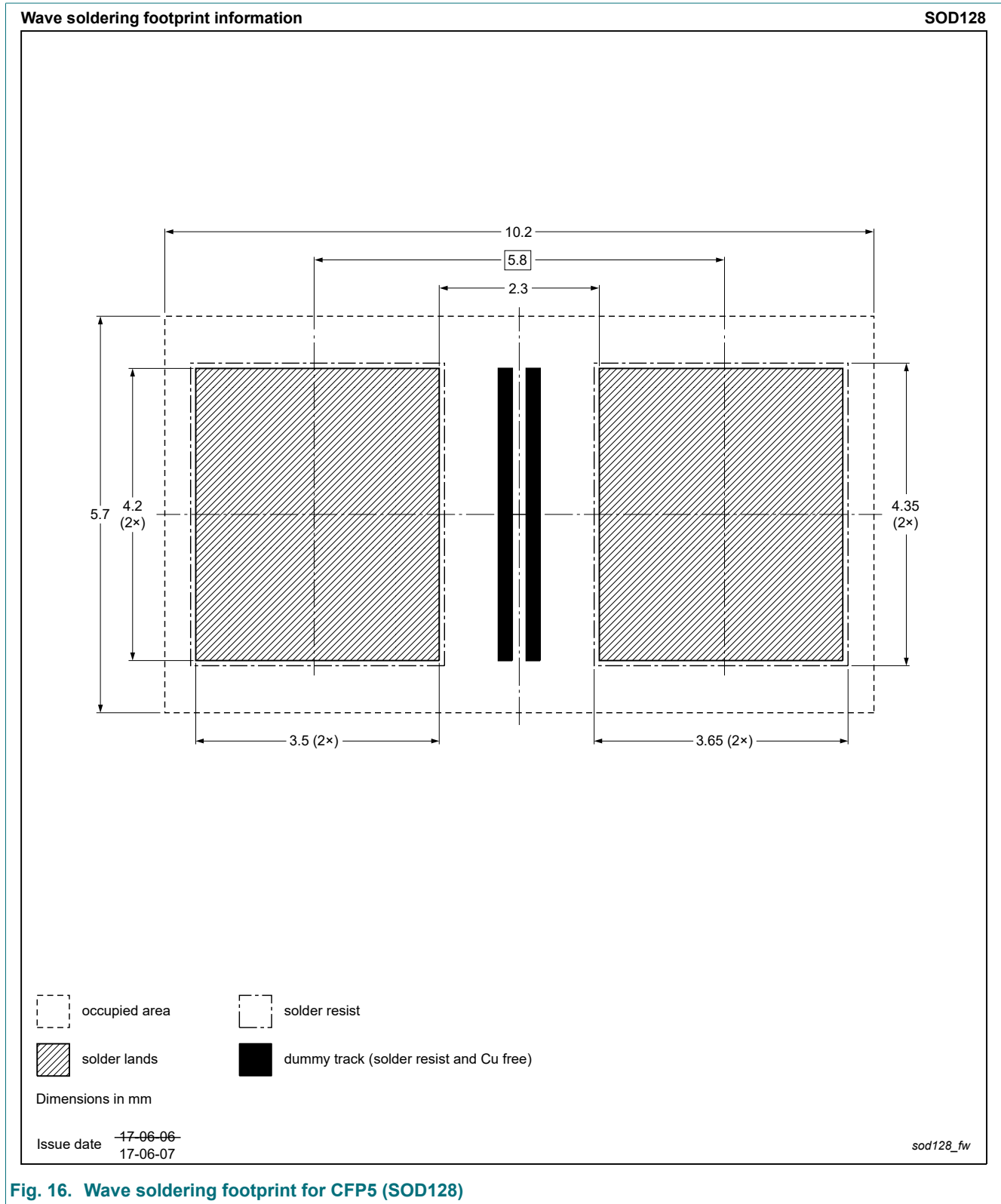


Fig. 16. Wave soldering footprint for CFP5 (SOD128)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|--|--------------------|---------------|--------------|
| PMEG6020EP v.2 | 20190228 | Product data sheet | - | PMEG6020EP_1 |
| Modifications: | <ul style="list-style-type: none">• Features and benefits: Capable for reflow and wave soldering added• Soldering: Wave soldering footprint added | | | |
| PMEG6020EP_1 | 20100317 | Product data sheet | - | - |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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- [2] The term 'short data sheet' is explained in section "Definitions".
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